

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1120	@ad<="20030909" and (257/734).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:13
S2	1413	@ad<="20030909" and 'controlled collapse chip connection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 11:28
S3	1	@ad<="20030909" and 'controlled collapse chip connection' same 'interconnection' and 'thick metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:27
S4	277	@ad<="20030909" and 'controlled collapse chip connection' same 'interconnection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:31
S5	5310	@ad<="20030909" and (257/690).ccls. or (257/700).ccls. or (257/737).ccls. or (257/738).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 09:09
S6	50	@ad<="20030909" and 'controlled collapse chip connection' and 'interconnection' same 'metal layers'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:31
S7	91	@ad<="20030909" and 'flip chip' same 'interconnection' same 'metal layers'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:31
S8	8889	@ad<="20030909" and (257/778).ccls. or (257/691-692).ccls. or (257/758-760).ccls. or (257/738).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 14:58
S9	560	@ad<="20030909" and 'metal' same 'interconnection' same 'bump' same 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:39
S10	2	@ad<="20030909" and 'thick metal' same 'interconnection' same 'bump' same 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:28

S11	14	@ad<="20030909" and 'metal' same 'interconnection' same 'bump' same 'pad' same 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:34
S12	1	@ad<="20030909" and 'interconnection' same 'bump' same 'large current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:35
S13	313	@ad<="20030909" and 'interconnection' same 'large current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:35
S14	2	@ad<="20030909" and 'interconnect' same 'large current' same 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:35
S15	201	@ad<="20030909" and 'metal' with 'interconnection' same 'bump' with 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:40
S16	1413	@ad<="20030909" and 'controlled collapse chip connection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:40
S17	20	S16 and 'metal' with 'interconnection' same 'bump' with 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:42
S18	348	S16 and 'interconnection' same 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:42
S19	300	S16 and 'interconnection' same 'bump' and 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:43
S20	117	S16 and 'interconnection' same 'bump' same 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:43
S21	48	S16 and 'interconnection' same 'bump' same 'metal' and 'IC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/03 15:43

S22	4840	@ad<="20030909" and (257/701).ccls. or (257/773).ccls. or (257/E23.021).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 09:10
S23	1490	@ad<="20030909" and (257/E23.069).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 09:11
S24	1	"20020020898".PN.	US-PGPUB	OR	ON	2004/12/06 10:20
S25	1	"6110806".PN.	USPAT; USOCR	OR	ON	2004/12/06 10:22
S26	1	"6010956".PN.	USPAT; USOCR	OR	ON	2004/12/06 10:22
S27	1	"5757072".PN.	USPAT; USOCR	OR	ON	2004/12/06 10:22
S28	1	"5353498".PN.	USPAT; USOCR	OR	ON	2004/12/06 10:23
S29	3	@ad<="20030909" and 'C4' same 'thick metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 11:06
S31	172	@ad<="20030909" and 'C4' with 'connection' with 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 12:49
S32	1	@ad<="20030909" and 'orthogonal' same 'connection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:06
S33	772	@ad<="20030909" and 'interconnection' same 'metal layer' with 'barrier'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:07
S34	52	@ad<="20030909" and 'interconnection' same 'metal layer' with 'diffusion barrier'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:15
S35	953	@ad<="20030909" and 'metal layer' with 'diffusion barrier'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 12:15
S37	37	@ad<="20030909" and 'controlled collapse chip connection' and 'die' and 'substrate' and 'high current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 14:33

S38	13	@ad<="20030909" and 'controlled collapse chip connection' and 'die' and 'substrate' and 'large current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 11:31
S39	160	@ad<="20030909" and 'C4' and 'die' and 'substrate' and 'high current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 11:30
S40	47	@ad<="20030909" and 'C4' and 'die' and 'substrate' and 'large current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 11:31
S41	302	@ad<="20030909" and 'controlled collapse chip connection' and 'die' and 'substrate' and 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 11:31
S43	195	@ad<="20030909" and 'controlled collapse chip connection' with 'bumps' and 'solder bump' and 'die' and 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 12:47
S44	36	Kim-Sarah-E.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 11:41
S45	77	@ad<="20030909" and 'C4 bumps' and 'solder bump' and 'die' and 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 12:27
S46	62	@ad<="20030909" and 'C4 bump' and 'solder bump' and 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 12:35
S47	18	@ad<="20030909" and 'C4 bump' same 'metal' and 'solder bump' and 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 12:35
S48	1	"6255151".PN.	USPAT; USOCR	OR	ON	2005/04/04 12:37
S49	68	@ad<="20030909" and 'C4' with 'connection' with 'metal' same 'bumps'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 13:04

S50	4	(("6255675") or ("6341418")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 13:05
S51	2	"20030218246"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 13:06
S52	472	@ad<="20030909" and 'Chip Size Package' and 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 13:10
S53	39	@ad<="20030909" and 'Chip Size Package' same 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 13:21
S54	2	"20040227251"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 13:18
S55	35	@ad<="20030909" and 'CSP' and 'C4' and 'interconnect' and 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 14:20
S56	2	@ad<="20030909" and 'CSP' and 'C4 bumps' and 'interconnect' and 'solder bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 13:23
S57	2	("6627994").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 14:17
S58	35	@ad<="20030909" and 'CSP' same 'C4'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 14:21
S59	0	@ad<="20030909" and 'CSP' same 'C4 bumps'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 14:21

S60	936	@ad<="20030909" and 'CSP' same 'bumps'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 14:21
S61	7	@ad<="20030909" and 'controlled collapse chip connection bumps' and 'high current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 14:36
S62	30	@ad<="20030909" and 'controlled collapse chip connection bumps'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 14:48
S63	664	@ad<="20030909" and 'solder ball' with 'C4'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/04 14:49